

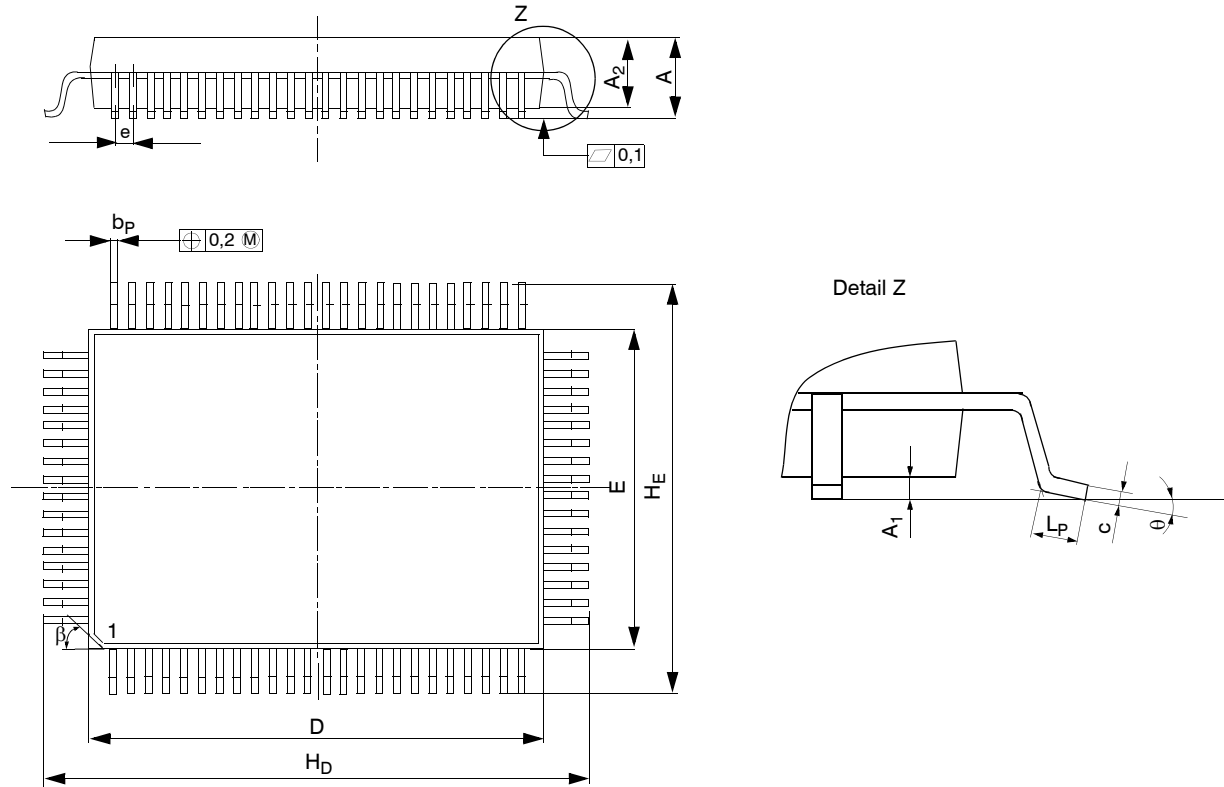
	Package PQFP80	MDS 717
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Supersedes
Edition 11.92
1. Amendment 02.93

Dimensions in millimetres

Based on JEDEC : MO-112AA-1

1 Dimensions



Dimensions of Sub-Group B1	
e_{nom}	0,80
A_{max}	3,20
b_{Pmin}	0,25
b_{Pmax}	0,45
H_{Emin}	17,60
H_{Emax}	18,20
H_{Dmin}	23,60
H_{Dmax}	24,20
L_{Pmin}	0,65

2 Weight $\leq 1,6$ g

3 Package Body Material Low Stress Epoxy

4 Lead Material FeNi-Alloy or Cu-Alloy

5 Lead Finish solder plating

6 Lead Form z-bends

Dimensions of Sub-Group C1	
A_{min}	2,75
A_{1min}	0,15
A_{1max}	0,38
A_{2min}	2,60
A_{2max}	2,80
c_{min}	0,12
c_{max}	0,25
D_{min}	19,90
D_{max}	20,10
E_{min}	13,90
E_{max}	14,10
θ_{min}	0°
θ_{max}	10°
β	45°

Zentrum Mikroelektronik Dresden GmbH		
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